

Special Issue

Additively Manufactured Flexible RF Structures for Next Generation of Wireless Applications

Message from the Guest Editors

Modern communication systems require multiple multiband radio frequency (RF) components such as antennas, electromagnetic interference shielding structures and matching networks to be packaged together into a single low-cost module. Traditional subtractive manufacturing technologies (SMTs) are proving to be insufficient to meet the demands of rapidly growing communication industry due to their high cost, longer lead time and production of high volume of environmentally harmful chemical waste. We are pleased to invite you to highlight your work in the Special Issue. The topics of interest include, but are not limited to, the following:

- Energy harvesting system;
- Millimeter wave flexible antennas and systems;
- Inkjet/3D/4D printed RF structures for 6G and beyond;
- Miniaturized antennas and modules for hearable/wearable devices;
- Transparent and low-profile antennas;
- Body worn antennas and RF circuits for wireless communication and energy harvesting;
- Wearable antennas and systems for 5G/IoT and medical systems.

We look forward to your submissions.

Guest Editors

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Deadline for manuscript submissions

closed (28 February 2023)



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About the Journal

Message from the Editor-in-Chief

Electronics is a multidisciplinary journal designed to appeal to a diverse audience of research scientists, practitioners, and developers in academia and industry. The journal is devoted to fast publication of latest technological breakthroughs, cutting-edge developments, and timely reviews of current and emerging technologies related to the broad field of electronics. Experimental and theoretical results are published as regular peer-reviewed articles or as articles within Special Issues guestedited by leading experts in selected topics of interest.

Editor-in-Chief

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